



Thematic Network on Silicon on Insulator Technology, Devices and Circuits.
[IST-1-506653-CA]

EUROSOI "Who is Who" Guide

Name of the organisation

<i>Organization Legal name:</i>	Technical Research Centre of Finland
<i>Organization short name:</i>	VTT
<i>Internet homepage:</i>	www.vtt.fi

Contact person

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Other Senior Researchers: (up to 10 names, please include e-mail address)

Prof. Jouni Ahopelto, jouni.ahopelto@vtt.fi

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Experience and expertise fields: (50 words)

- Thick SOI materials by direct bonding for MEMS applications
- Thin SOI materials by hydrogen implantation and cold cut
- Transport measurement in thin SOI
- Velocity modulation transistors
- SOI based MEMS and SOI based integrated optical waveguides

Facilities and Equipment:

- 1800 m² clean room (class 10-1000)
- 0.6 µm polySi gate CMOS, 0.8 µm Mo gate CMOS with all associated equipment
- Backend processing equipment for wafer bumping, dicing and assembly
- Equipment for direct wafer bonding, backgrinding and chemical-mechanical planarization
- Equipment for physical characterization: SEM/EDX, RBS, AFM, SAM
- Wafer probing up to 110 GHz
- Low-temperature transport measurements down to 300 mK and upto 11 Tesla.
- Mentor Graphics / Cadence design software,
- Spice, APLAC simulation tools

Three last international research projects:

EU-IST projects:

NEAR, EXTRA, PHAT